Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # ATS1032-ND

ATS PART # ATS-50170P-C2-R0

Features & Benefits

maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

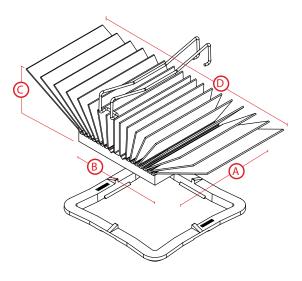
maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for standard height components from 3 to 4.5mm

Thermal Performance Table





AIR VELOCITY THERMAL RESISTANCE °C/W (DUCTED) FT/MIN M/S °C/W (UNDUCTED) 8.3 200 1.0 6.8 6.9 300 1.5 6 400 2.0 5.4 500 2.5 5 600 3.0 700 3.5 4.6 800 4.0 4.4

Product Details[†]

DIMENSION A	DIMENSION B	DIMENSION C [§]	DIMENSION D	TIM [‡]	FINISH
17	17	17.5	31.94	C1100F	BLUE-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters◆ Dimensions A & B refer to component size

S Dimension C = the height of the heat sink shown above

and does not include the height of the attachment method



